

# Product data sheet

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Semiconductor Compiance

## Silicon Epitaxial Planar Schottky Barrier Diode

for low current rectification and high speed switching applications

#### Features

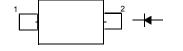
- Extremely small surface mounting type
- High reliability

 PINNING

 PIN
 DESCRIPTION

 1
 Cathode

 2
 Anode



SOD-523

#### Absolute Maximum Ratings (T<sub>a</sub> = 25 °C)

Parameter	Symbol	Value	Unit
Reverse Voltage	V <sub>R</sub>	30	V
Mean Rectifying Current	I <sub>F(AV)</sub>	200	mA
Peak Forward Surge Current (60 Hz for 1 Cyc.)	I <sub>FSM</sub>	1	А
Junction Temperature	Tj	125	°C
Storage Temperature Range	T <sub>stg</sub>	- 40 to + 125	°C

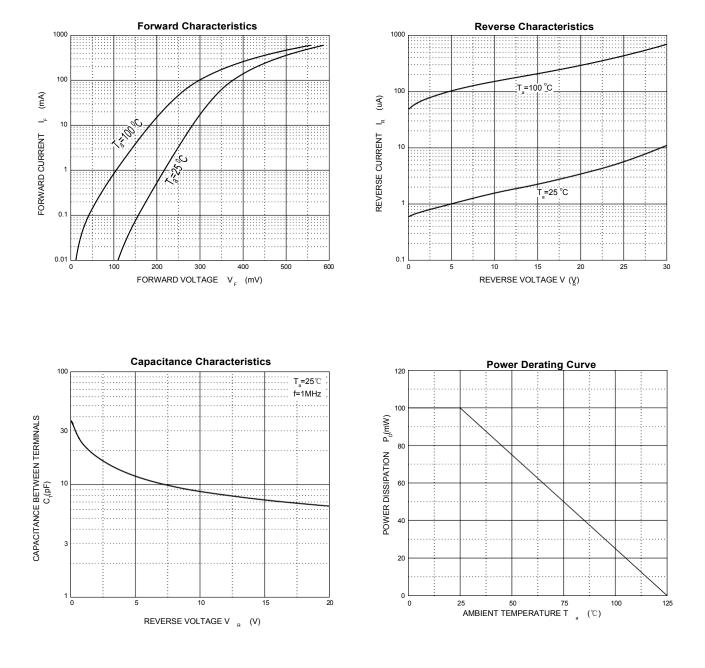
#### Characteristics at T<sub>a</sub> = 25 °C

Parameter	Symbol	Max.	Unit
Forward Voltage at I <sub>F</sub> = 200 mA	V <sub>F</sub>	0.6	V
Reverse Current at $V_R = 10 V$	I <sub>R</sub>	1	μA

Note: ESD sensitive product handling required.



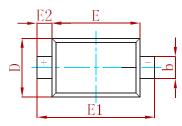


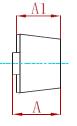


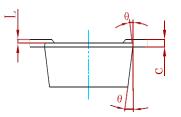




## PACKAGE MECHANICAL DATA

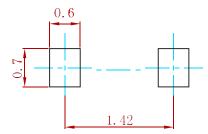






Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
С	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		300.0	3 REF
L	0.010	0.070	0.001	0.003
0	7° REF		7° F	REF

# Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.

3. The pad layout is for reference purposes only.

### **REEL SPECIFICATION**

P/N	PKG	QTY
RB520S-30-MS	SOD-523	3000



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